ABSTRACT OF THE DISCLOSURE

MOLDED TAPE SUPPORT FOR A MOLDED CIRCUIT PACKAGE PRIOR TO DICING

A molded electronic circuit package is described to which stabilizing tape can be attached using automatic or semi-automatic means. The stabilizing tape stabilizes the assembly for further processing operations such as dicing or attachment to a higher level package. The assembly comprises a substrate to which devices are attached. Molded caps are formed over the devices. Molded tape supports are formed at the same time as the molded caps and are located adjacent to opposite sides of the molded cap. The molded tape supports have the same height as the molded cap. The stabilizing tape can the be easily attached to the tops of the molded tape supports and the molded caps using automatic or semi-automatic means.

(FIGURE 2 IS SUGGESTED FOR PUBLICATION)